

## **Description**

The AO4410 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

SOP-8 **General Features** 

 $V_{DS} = 30V I_{D} = 15 A$ 

 $R_{DS(ON)} < 9m\Omega$  @  $V_{GS}=10V$ 

 $R_{DS(ON)} < 14m\Omega$  @  $V_{GS} = 4.5V$ 

**Application** 

Battery protection

Load switch

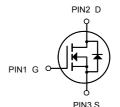
Uninterruptible power supply

**Package Marking and Ordering Information** Product ID Pack Marking Qty(PCS) AO4410 SOP-8 4410 XXX YYYY 3000

Absolute Maximum Ratings (T<sub>C</sub>=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit	
V <sub>DS</sub>	Drain-Source Voltage	30	V	
V <sub>G</sub> s	Gate-Source Voltage	±20	V	
I <sub>D</sub>	Drain Current-Continuous	15.0	Α	
I <sub>D</sub> (70 °C)	Drain Current-Continuous(Tc=70℃)	8.2	А	
Ірм	Pulsed Drain Current	42	А	
P <sub>D</sub>	Maximum Power Dissipation	1.5	W	
Eas	Single pulse avalanche energy (Note 5)	62	mJ	
TJ,TsTG	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$ C	
Rejc	euc Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>		°C/W	





N-Channel MOSFET



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.027		V/°C	
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =10A	V <sub>GS</sub> =10V , I <sub>D</sub> =10A 7.5		9	mΩ	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =8A		11	14		
$V_{GS(th)}$	Gate Threshold Voltage	V V I 250	1.2	1.5	2.5	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.8		mV/°C	
	Dunin Course Looke to Course	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA	
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		5.8		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.2	3.8	Ω	
Qg	Total Gate Charge (4.5V)			12.6	17.6		
Qgs	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		4.2	5.9	nC	
Q <sub>gd</sub>	Gate-Drain Charge			5.1	7.1		
T <sub>d(on)</sub>	Turn-On Delay Time			6.2	12.4		
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		59	106		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =10A		27.6	55	ns	
Tf	Fall Time			8.4	16.8		
Ciss	Input Capacitance			1317	1845		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		163	228.2	pF	
Crss	Reverse Transfer Capacitance			131	183.4		

## **Diode Characteristics**

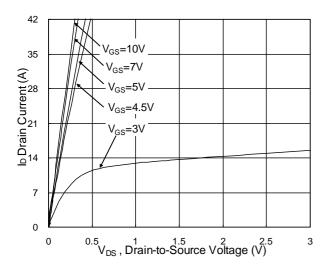
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,5</sup>	V- V- OV Force Current			10.3	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			42	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			12.5		nS
Q <sub>rr</sub>	Reverse Recovery Charge	lF=10A , dl/dt=100A/μs , Tյ=25°C		5		nC

#### Note

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =35A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

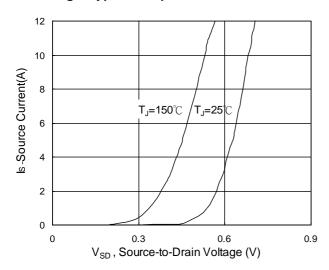


Fig.3 Forward Characteristics of reverse

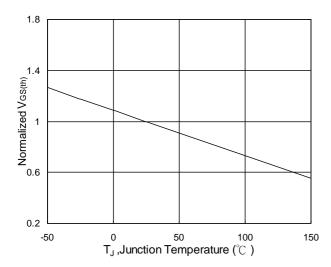


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

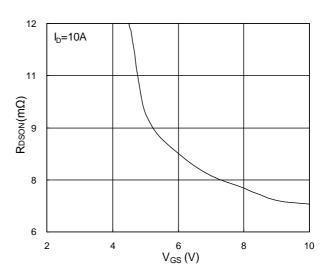
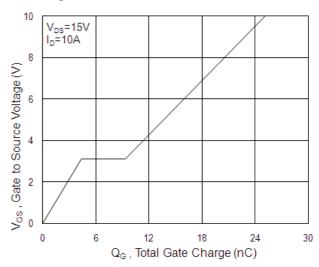


Fig.2 On-Resistance vs. Gate-Source



**Fig.4 Gate-Charge Characteristics** 

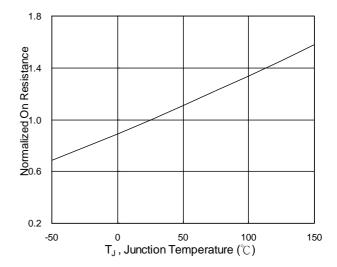
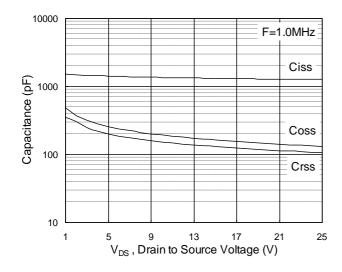


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



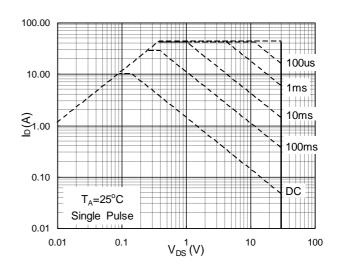


Fig.7 Capacitance

Fig.8 Safe Operating Area

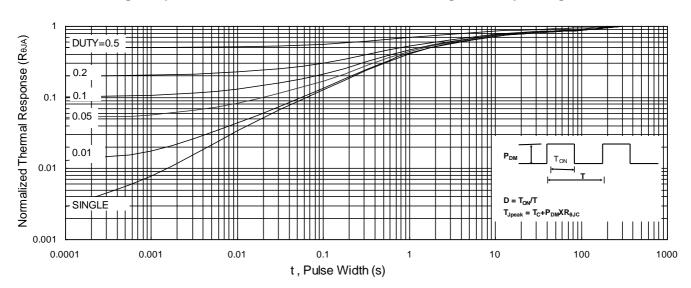


Fig.9 Normalized Maximum Transient Thermal Impedance

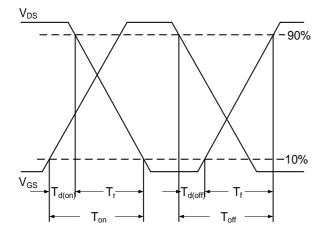


Fig.10 Switching Time Waveform

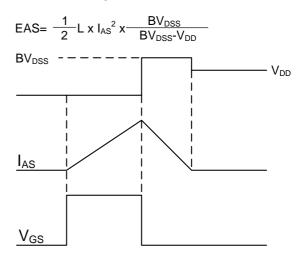
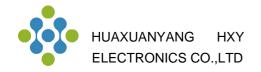
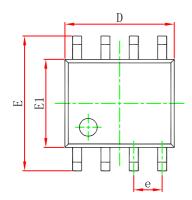
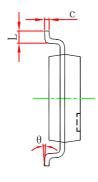


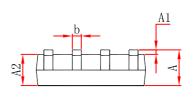
Fig.11 Unclamped Inductive Switching Waveform



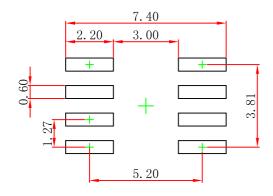
# **SOP-8 Package Outline Dimensions**







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1. 350	1.750	0.053	0.069	
A1	0.100	0. 250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
c	0.170	0. 250	0.007	0.010	
D	4.800	5.000	0.189	0. 197	
e	1. 270 (BSC)		0.050 (BSC)		
E	5.800	6. 200	0. 228	0. 244	
E1	3.800	4.000	0.150	0. 157	
L	0.400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
  3.The pad layout is for reference purposes only.



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